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**Electromagnetic compatibility (EMC) –
Part 4-6: Testing and measurement techniques – Immunity to conducted
disturbances, induced by radio-frequency fields**

**Compatibilité électromagnétique (CEM) –
Partie 4-6: Techniques d'essai et de mesure – Immunité aux perturbations
conduites, induites par les champs radioélectriques**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ELECTROMAGNETIC COMPATIBILITY (EMC) –

Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields

FOREWORD

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International Standard IEC 61000-4-6 has been prepared by subcommittee 77B: High frequency phenomena, of IEC technical committee 77: Electromagnetic compatibility.

It forms Part 4-6 of IEC 61000. It has the status of a basic EMC publication in accordance with IEC Guide 107.

This fourth edition cancels and replaces the third edition published in 2008 and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) use of the CDNs;
- b) calibration of the clamps;
- c) reorganization of Clause 7 on test setup and injection methods;

- d) Annex A which is now dedicated to EM and decoupling clamps;
- e) Annex G which now addresses the measurement uncertainty of the voltage test level;
- f) informative Annexes H, I and J which are new.

The text of this standard is based on the following documents:

FDIS	Report on voting
77B/691/FDIS	77B/704/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61000 series, published under the general title *Electromagnetic compatibility (EMC)*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

IEC 61000 is published in separate parts according to the following structure:

Part 1: General

General considerations (introduction, fundamental principles)

Definitions, terminology

Part 2: Environment

Description of the environment

Classification of the environment

Compatibility levels

Part 3: Limits

Emission limits

Immunity limits (in so far as they do not fall under the responsibility of the product committees)

Part 4: Testing and measurement techniques

Measurement techniques

Testing techniques

Part 5: Installation and mitigation guidelines

Installation guidelines

Mitigation methods and devices

Part 6: Generic standards

Part 9: Miscellaneous

Each part is further subdivided into several parts, published either as international standards or as technical specifications or technical reports, some of which have already been published as sections. Others will be published with the part number followed by a dash and a second number identifying the subdivision (example: IEC 61000-6-1).

This part is an international standard which gives immunity requirements and test procedures related to conducted disturbances induced by radio-frequency fields.

ELECTROMAGNETIC COMPATIBILITY (EMC) –

Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields

1 Scope

This part of IEC 61000 relates to the conducted immunity requirements of electrical and electronic equipment to electromagnetic disturbances coming from intended radio-frequency (RF) transmitters in the frequency range 150 kHz up to 80 MHz. Equipment not having at least one conducting wire and/or cable (such as mains supply, signal line or earth connection) which can couple the equipment to the disturbing RF fields is excluded from the scope of this publication.

NOTE 1 Test methods are defined in this part of IEC 61000 to assess the effect that conducted disturbing signals, induced by electromagnetic radiation, have on the equipment concerned. The simulation and measurement of these conducted disturbances are not adequately exact for the quantitative determination of effects. The test methods defined are structured for the primary objective of establishing adequate repeatability of results at various facilities for quantitative analysis of effects.

The object of this standard is to establish a common reference for evaluating the functional immunity of electrical and electronic equipment when subjected to conducted disturbances induced by RF fields. The test method documented in this part of IEC 61000 describes a consistent method to assess the immunity of an equipment or system against a defined phenomenon.

NOTE 2 As described in IEC Guide 107, this standard is a basic EMC publication for use by product committees of the IEC. As also stated in Guide 107, the IEC product committees are responsible for determining whether this immunity test standard should be applied or not, and if applied, they are responsible for determining the appropriate test levels and performance criteria.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050 (all parts), *International Electrotechnical Vocabulary (IEV)* (available at <<http://www.electropedia.org>>)

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